

# THC63LVDM83E

28bits LVTTI/LVDS to 4ch LVDS Serializer/Transmitter

## General Description

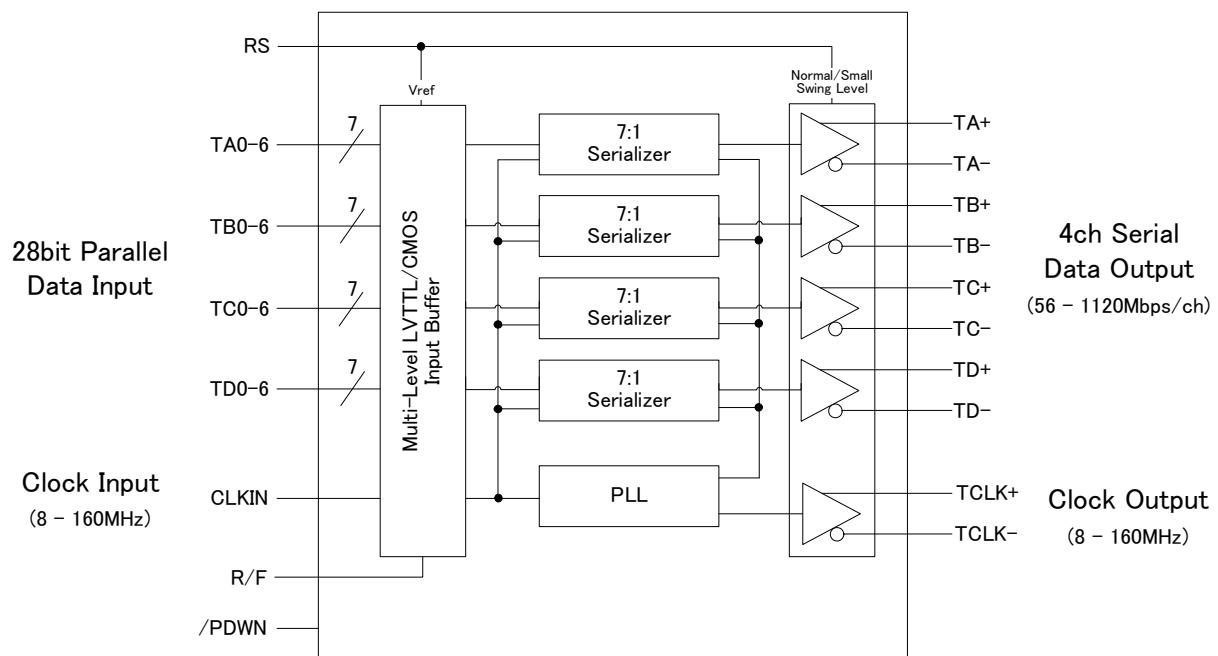
The THC63LVDM83E is a general purpose data serializer based on LVDS technology with no overhead for protocol or encoding.

The THC63LVDM83E converts 28bits of CMOS/TTL data into 4ch LVDS data stream. The transmitter can be programmed for rising edge or falling edge clocks through a dedicated pin.

## Features

- 49pin 0.65mm pitch VFBGA Package
- Wide Input clock range: 8-160MHz
- Maximum total throughput 4.48Gbit/s@160MHz
- 3.3/2.5/1.8/1.2V voltage logic input
- LVDS swing is reducible by RS-pin to reduce EMI and power consumption.
- PLL requires no external components.
- On chip jitter filtering.
- Spread Spectrum Clock input tolerant.
- Power down mode.
- Input clock triggering edge is selectable by R/F-pin.
- Operates from a Single 3.3V Supply and 110mW(typ.) at 75MHz.

## Block Diagram



Ball Out**TOP VIEW**

	1	2	3	4	5	6	7
A	TA6	TA5	TA4	TA3	TA2	TA1	TA0
B	TB4	TD3	TD2	TD1	TD0	TA-	TA+
C	TB5	TB0	GND	VCC	RS	TB-	TB+
D	TB6	TB1	GND	LVDS VCC	LVDS VCC	TC-	TC+
E	TC0	TB2	GND	PLL VCC	R/F	TCLK-	TCLK+
F	TC1	TB3	TD4	TD5	TD6	TD-	TD+
G	TC2	TC3	TC4	TC5	TC6	CLKIN	/PDWN

Pin Description

Pin Name	Pin #	Type	Description			
TA+, TA-	B7, B6	LVDS Output	4ch Serial Data Output			
TB+, TB-	C7, C6					
TC+, TC-	D7, D6		Clock Output			
TD+, TD-	F7, F6					
TCLK+, TCLK-	E7, E6	3.3V LVTTL 2.5/1.8/1.2V CMOS Digital Input	28bit Parallel Data Input			
TA0 ~ TA6	A7,A6,A5,A4,A3,A2,A1					
TB0 ~ TB6	C2,D2,E2,F2,B1,C1,D1					
TC0 ~ TC6	E1,F1,G1,G2,G3,G4,G5		Clock Input			
TD0 ~ TD6	B5,B4,B3,B2,F3,F4,F5					
CLKIN	G6	3.3V LVTTL Digital Input	Power Down Control H: Normal operation L: Power Down (All output are Hi-Z.)			
/PDWN	G7		Input Clock Triggering Edge Select H: Rising edge L: Falling edge			
R/F	E5		Input/output Level Select and 2.5/1.8/1.2V Logic level Reference Voltage Input			
RS	C5	Analog Input	RS-pin Input Voltage Setting	Data/Clock Input Voltage	Input Buffer Vref	LVDS Output VOD
			VCC	3.3V	VCC/2	350mV
			1.25V	2.5V	1.25V	
			0.9V	1.8V	0.9V	
			0.6V	1.2V	0.6V	
			GND	3.3V	VCC/2	200mV
VCC	C4	Power	Power Supply Pin for LVTTL/CMOS input and digital circuit.			
GND	C3,D3,E3		Ground Pins for Common.			
LVDS VCC	D4,D5		Power Supply Pins for LVDS Outputs.			
PLL VCC	E4		Power Supply Pin for PLL circuit.			

**Absolute Maximum Ratings**

Parameter	Min	Max	Units
Supply Voltage	-0.3	+4.0	V
LVTTL/CMOS and Analog Input Voltage	-0.3	VCC + 0.3	V
LVDS Transmitter Output Voltage	-0.3	VCC + 0.3	V
Output Current	-30	30	mA
Junction Temperature	-	+125	°C
Storage Temperature	-55	+125	°C
Reflow Peak Temperature	-	+260	°C
Reflow Peak Temperature Time	-	10	sec
Maximum Power Dissipation @+25°C	-	1.2	W

**Recommended Operating Conditions**

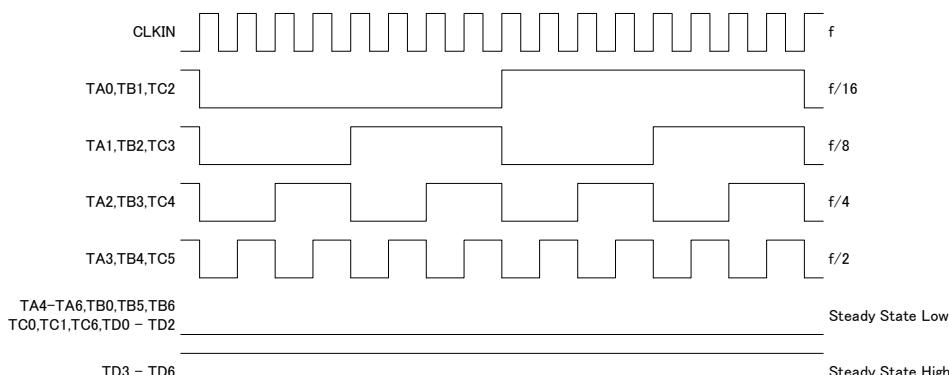
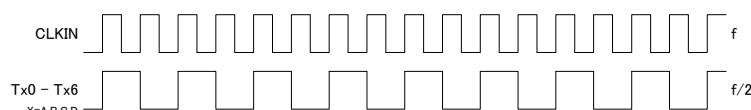
Symbol	Parameter	Min	Typ	Max	Units
VCC	All Supply Voltage	3.0	3.3	3.6	V
Ta	Operating Ambient Temperature	0	25	+70	°C
CLKIN	Clock Frequency	8	-	160	MHz

**Power Consumption**

VCC = 3.0~3.6V, Ta= 0~+70°C

Symbol	Parameter	Conditions	Typ*	Max	Units
I <sub>TCCW</sub>	LVDS Transmitter Operating Current Gray Scale Pattern 16(Fig.1)	RL=100Ω, CL=5pF, f=85MHz RS=VCC, (RS=GND)	42 (34)	-	mA
		RL=100Ω, CL=5pF, f=160MHz RS=VCC, (RS=GND)	58 (50)	-	mA
	LVDS Transmitter Operating Current Worst Case Pattern(Fig.2)	RL=100Ω, CL=5pF, f=85MHz RS=VCC, (RS=GND)	45 (36)	67 (56)	mA
		RL=100Ω, CL=5pF, f=160MHz RS=VCC, (RS=GND)	63 (55)	92 (80)	mA
I <sub>TCCS</sub>	LVDS Transmitter Power Down Current		-	10	µA

\*Typ values are at VCC=3.3V, Ta = +25°C

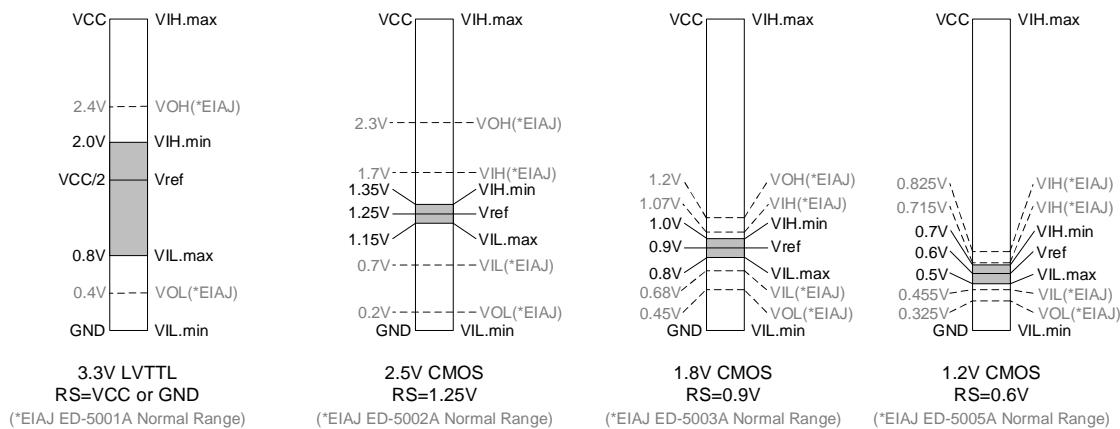
**Figure 1. 16 Grayscale Pattern****Figure 2. Worst Case Pattern**

## LVTTL/CMOS DC Specifications

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V <sub>IH</sub>	High Level Input Voltage	3.3V LVTTL V <sub>ref</sub> = VCC/2	2.0	-	VCC	V
		2.5/1.8/1.2V CMOS V <sub>ref</sub> = RS Input Voltage	V <sub>ref</sub> +0.1	-	VCC	
V <sub>IL</sub>	Low Level Input Voltage	3.3V LVTTL V <sub>ref</sub> = VCC/2	GND	-	0.8	V
		2.5/1.8/1.2V CMOS V <sub>ref</sub> = RS Input Voltage	GND	-	V <sub>ref</sub> -0.1	
I <sub>INC</sub>	Input Current	GND ≤ V <sub>IN</sub> ≤ VCC	-	-	±10	μA

\*Typ values are at VCC=3.3V, Ta = +25°C.



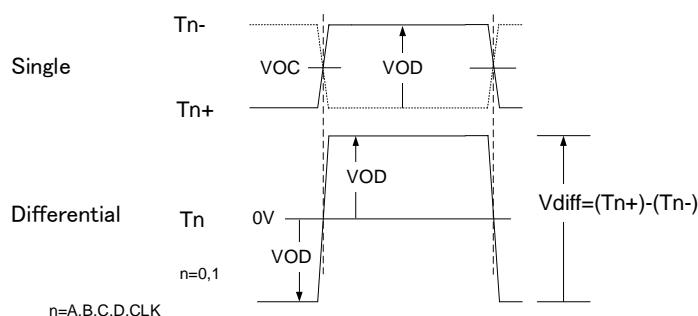
**Figure 3. LVTTL/CMOS Digital Input Compatibility**

## LVDS DC Specifications

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
VOD	Differential Output Voltage	RS=VCC, 0.6 ~ 1.4V RL=100Ω	250	350	450	mV
		RS=GND RL=100Ω	120	200	300	mV
ΔVOD	Change in VOD between complementary output states	RL=100Ω	-	-	35	mV
VOC	Common Mode Voltage	RL=100Ω	1.125	1.25	1.375	V
ΔVOC	Change in VOC between complementary output states	RL=100Ω	-	-	35	mV
Ios	Output Short Circuit Current	V <sub>OUT</sub> =GND, RL=100Ω	-	-	-24	mA
Ioz	Output TRI-STATE Current	/PDWN=GND, V <sub>OUT</sub> =GND to VCC	-	-	±10	μA

\*Typ values are at VCC=3.3V, Ta = +25°C.



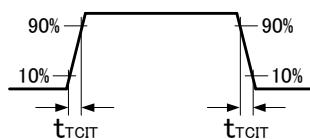
**Figure 4. LVDS DC Specifications**

### LVTTL/CMOS AC Specifications

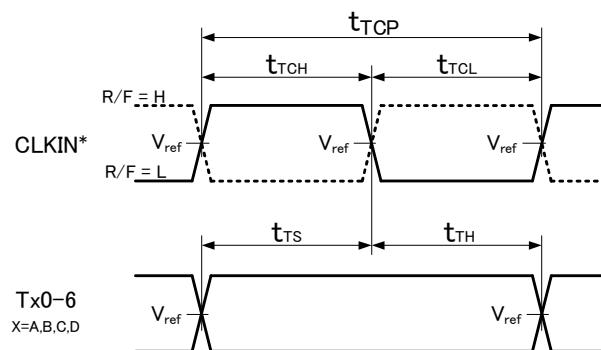
Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Min	Typ	Max	Units
t <sub>TCTR</sub>	CLKIN Transition Time	-	-	5.0	ns
t <sub>TCP</sub>	CLKIN Period	6.25	T	125	ns
t <sub>TCH</sub>	CLKIN High Time	0.35T	0.5T	0.65T	ns
t <sub>TCL</sub>	CLKIN Low Time	0.35T	0.5T	0.65T	ns
t <sub>TCD</sub>	CLKIN to TCLK+/- Delay	-	3T	-	ns
t <sub>TS</sub>	Tx0-6 Setup time to CLKIN	2.0	-	-	ns
t <sub>TH</sub>	Tx0-6 Hold time to CLKIN	0.0	-	-	ns

\*Typ values are at VCC=3.3V, Ta = +25°C



**Figure 5. CLKIN Transmission Time**



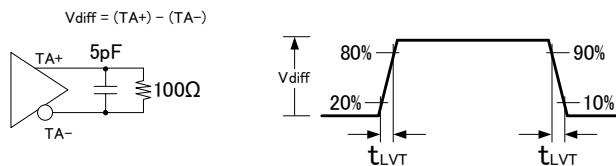
**Figure 6. LVTTL/CMOS Input Timings**

## LVDS AC Specifications

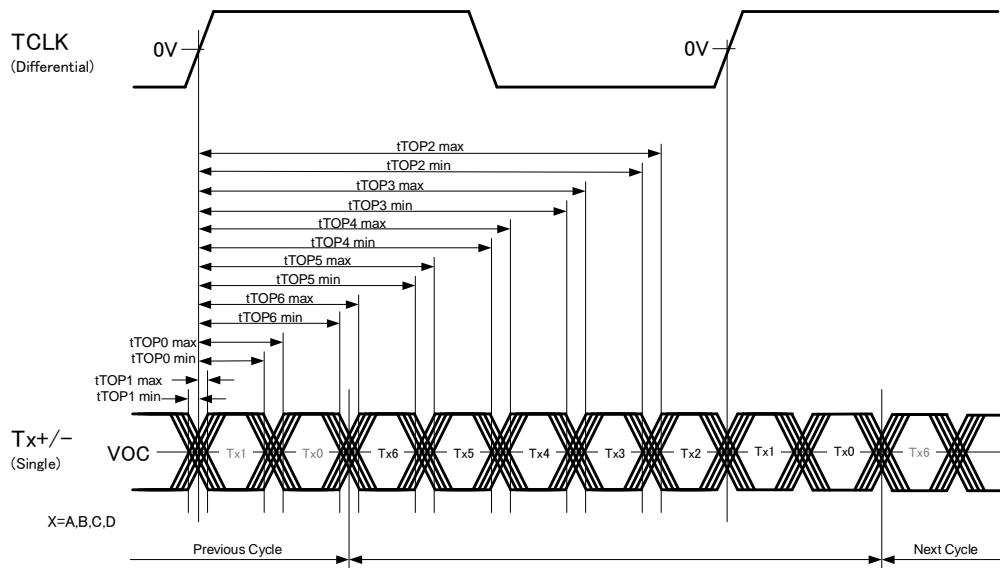
Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Min	Typ	Max	Units
$t_{LVT}$	LVDS Transition Time	-	0.6	1.5	ns
$t_{TOP1}$	Output Data Position0 ( $T=6.25\text{ns} \sim 20\text{ns}$ )	-0.15	0.0	+0.15	ns
$t_{Top0}$	Output Data Position1 ( $T=6.25\text{ns} \sim 20\text{ns}$ )	$T/7-0.15$	$T/7$	$T/7+0.15$	ns
$t_{Top6}$	Output Data Position2 ( $T=6.25\text{ns} \sim 20\text{ns}$ )	$2T/7-0.15$	$2T/7$	$2T/7+0.15$	ns
$t_{Top5}$	Output Data Position3 ( $T=6.25\text{ns} \sim 20\text{ns}$ )	$3T/7-0.15$	$3T/7$	$3T/7+0.15$	ns
$t_{Top4}$	Output Data Position4 ( $T=6.25\text{ns} \sim 20\text{ns}$ )	$4T/7-0.15$	$4T/7$	$4T/7+0.15$	ns
$t_{Top3}$	Output Data Position5 ( $T=6.25\text{ns} \sim 20\text{ns}$ )	$5T/7-0.15$	$5T/7$	$5T/7+0.15$	ns
$t_{Top2}$	Output Data Position6 ( $T=6.25\text{ns} \sim 20\text{ns}$ )	$6T/7-0.15$	$6T/7$	$6T/7+0.15$	ns

\*Typ values are at  $VCC=3.3V$ ,  $Ta = +25^\circ C$



**Figure 7. LVDS Output Load and Transmission Time**



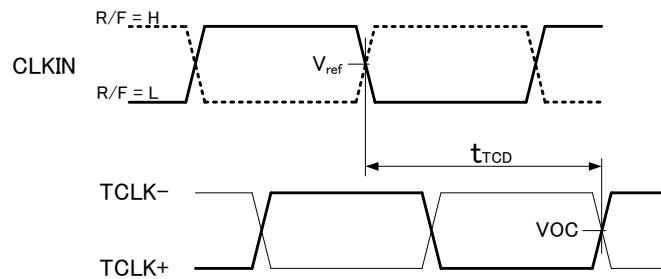
**Figure 8. LVDS Output Data Position**

## Input to Output AC Specifications

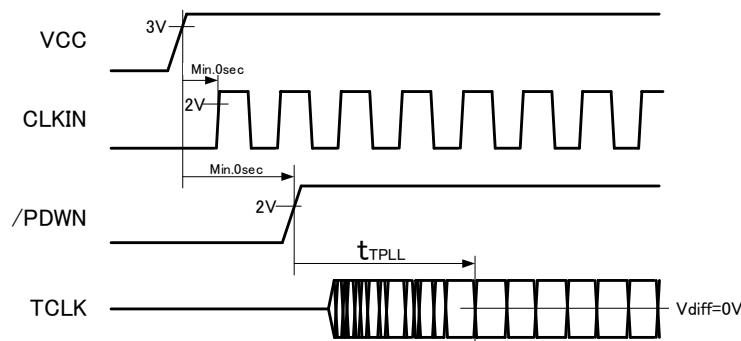
Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Min	Typ	Max	Units
$t_{TCD}$	CLKIN to TCLK+/- Delay	-	3T	-	ns
$t_{TPLL}$	Phase Lock Loop Set	-	-	10.0	ms

\*Typ values are at VCC=3.3V, Ta = +25°C



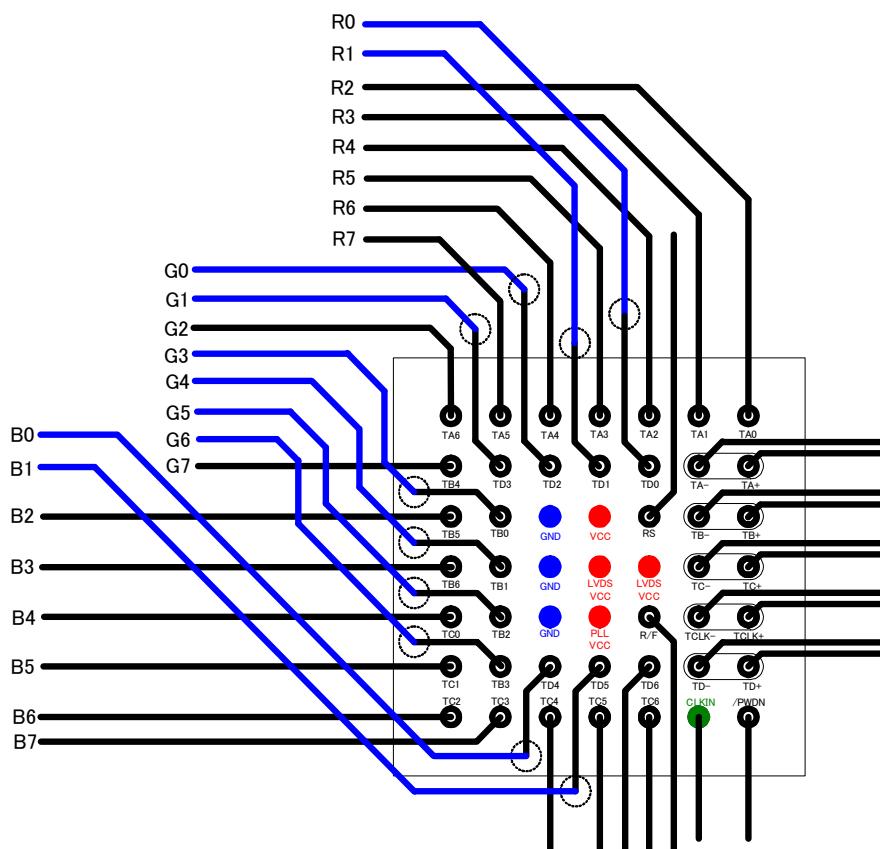
**Figure 9. CLKIN to TCLK+/- Delay**



**Figure 10. PLL Set Time**

Board Layout ExampleTOP VIEW

	1	2	3	4	5	6	7	
A	TA6	TA5	TA4	TA3	TA2	TA1	TA0	A
B	TB4	TD3	TD2	TD1	TD0	TA-	TA+	B
C	TB5	TB0	GND	VCC	RS	TB-	TB+	C
D	TB6	TB1	GND	LVDS VCC	LVDS VCC	TC-	TC+	D
E	TC0	TB2	GND	PLL VCC	R/F	TCLK-	TCLK+	E
F	TC1	TB3	TD4	TD5	TD6	TD-	TD+	F
G	TC2	TC3	TC4	TC5	TC6	CLKIN	/PDWN	G
	1	2	3	4	5	6	7	



## Note

### 1) Cable Connection and Disconnection

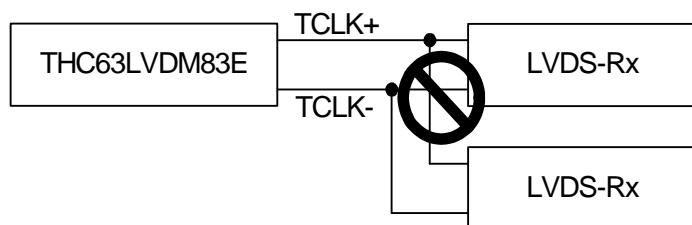
Don't connect and disconnect the LVDS cable, when the power is supplied to the system.

### 2) GND Connection

Connect the each GND of the PCB which THC63LVDM83E and LVDS-Rx on it. It is better for EMI reduction to place GND cable as close to LVDS cable as possible.

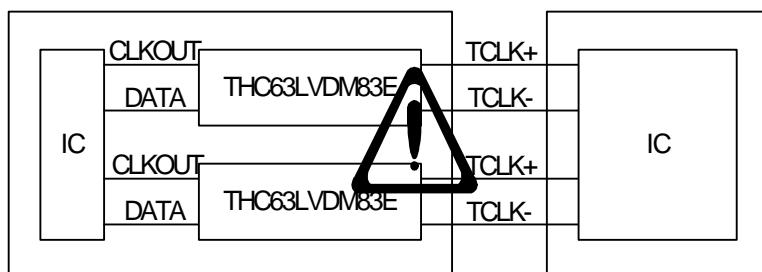
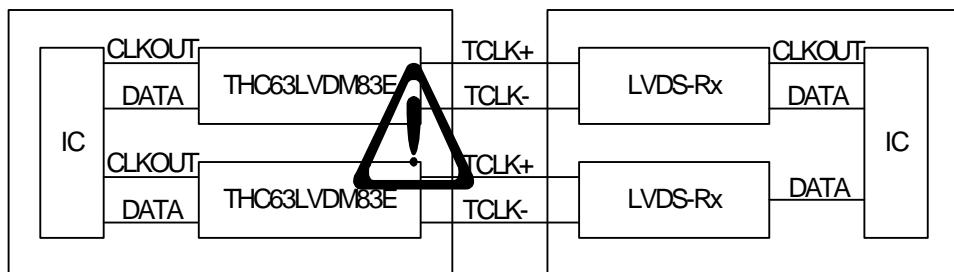
### 3) Multi Drop Connection

Multi drop connection is not recommended.

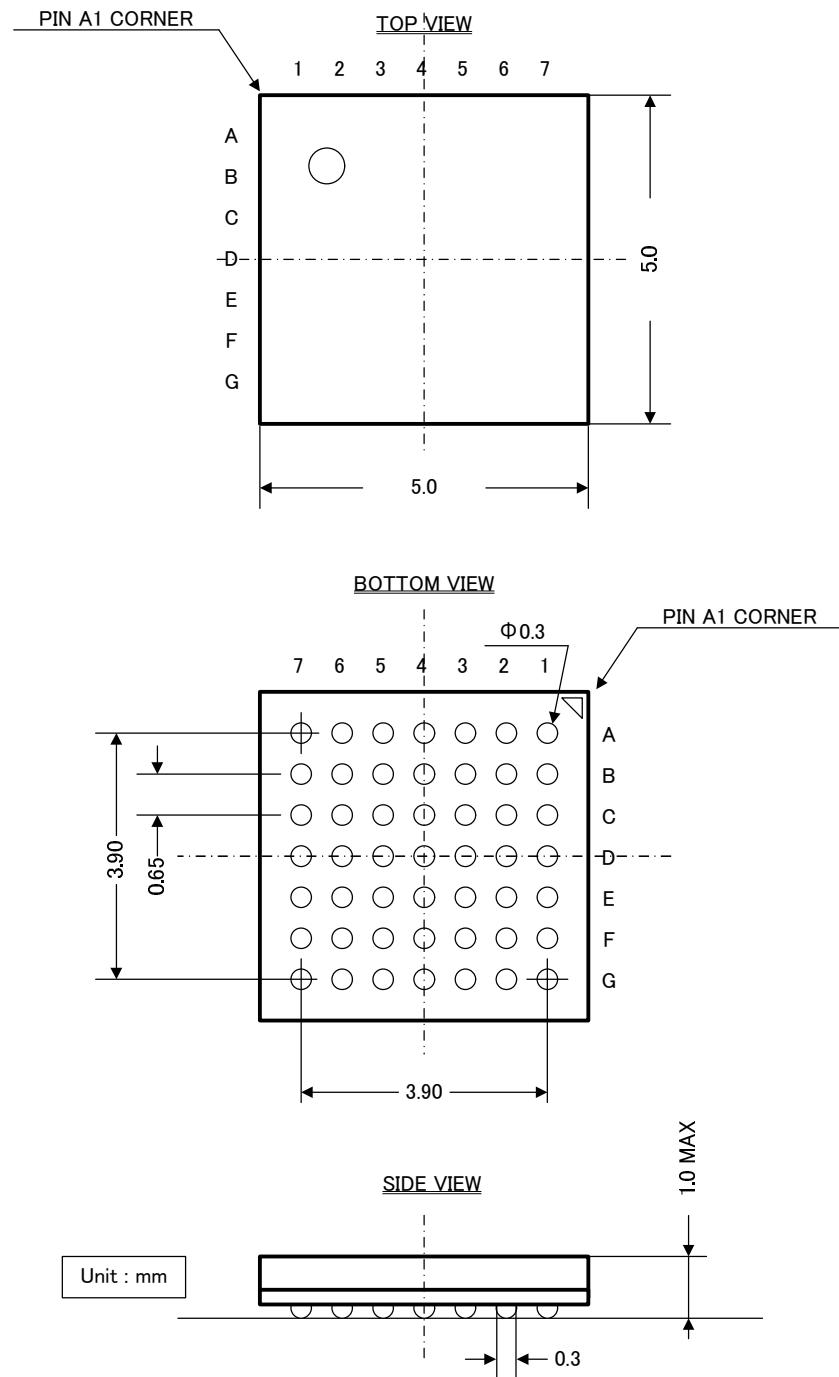


### 4) Asynchronous use

Asynchronous using such as following systems are not recommended.



## Package



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10. The product or peripheral parts may be damaged by a surge in voltage over the absolute maximum ratings or malfunction, if pins of the product are shorted by such as foreign substance. The damages may cause a smoking and ignition. Therefore, you are encouraged to implement safety measures by adding protection devices, such as fuses.

**THine Electronics, Inc.**

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